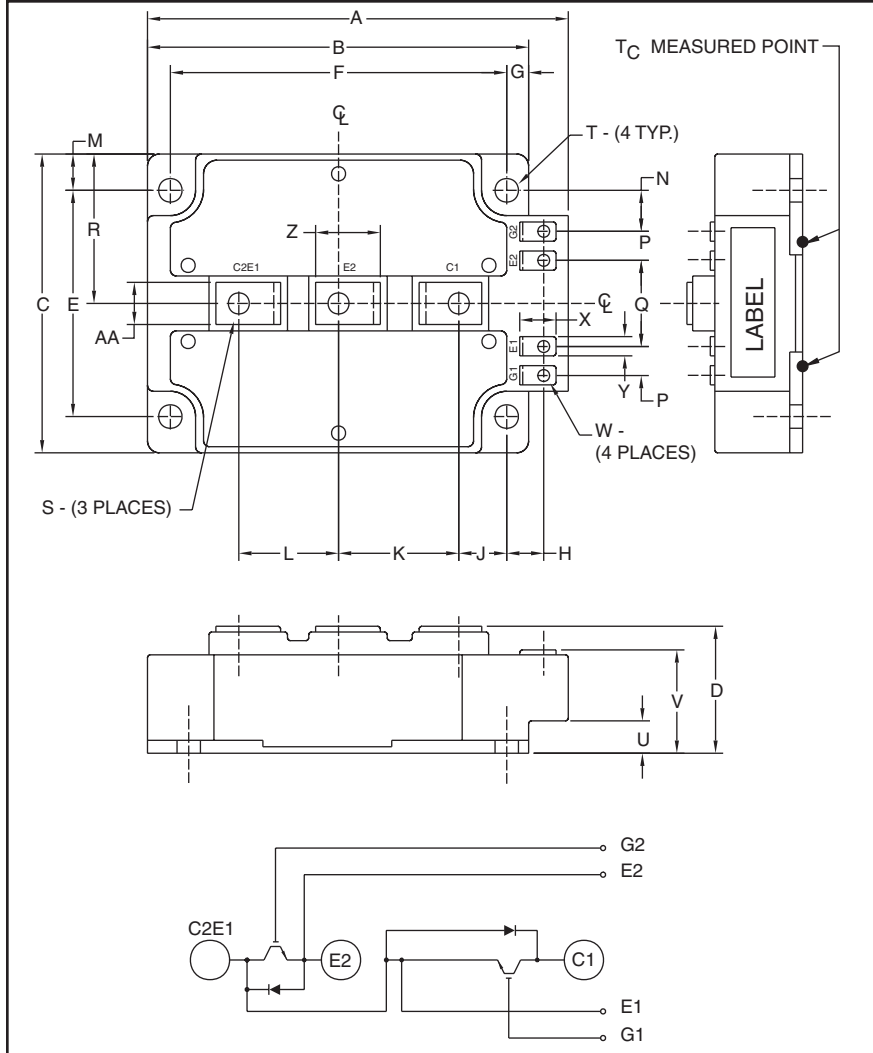


### Dual IGBTMOD™ A-Series Module 400 Amperes/1700 Volts



Outline Drawing and Circuit Diagram

| Dimensions | Inches          | Millimeters    |
|------------|-----------------|----------------|
| A          | 5.51            | 140.0          |
| B          | 5.12            | 130.0          |
| C          | 5.12            | 130.0          |
| D          | 1.38+0.04/-0.02 | 35.0+1.0/-0.5  |
| E          | 4.33+0.04/-0.02 | 110.0+1.0/-0.5 |
| F          | 4.33+0.04/-0.02 | 110.0+1.0/-0.5 |
| G          | 0.39            | 10.0           |
| H          | 0.45            | 11.5           |
| J          | 0.54            | 13.8           |
| K          | 1.72            | 43.8           |
| L          | 1.42            | 36.0           |
| M          | 0.39            | 10.0           |
| N          | 0.80            | 20.4           |

| Dimensions | Inches          | Millimeters   |
|------------|-----------------|---------------|
| P          | 0.57            | 14.5          |
| Q          | 1.57            | 40.0          |
| R          | 2.56            | 65.0          |
| S          | M8              | M8            |
| T          | 0.26 Dia.       | 6.5 Dia.      |
| S          | 0.32            | 8.0           |
| V          | 0.97+0.04/-0.02 | 24.5+1.0/-0.5 |
| W          | M4              | M4            |
| X          | 0.59            | 15.0          |
| Y          | 0.35            | 9.0           |
| Z          | 1.02            | 26.0          |
| AA         | 0.79            | 20.0          |



#### Description:

Powerex IGBTMOD™ Modules are designed for use in switching applications. Each module consists of two IGBT Transistors in a half-bridge configuration with each transistor having a reverse-connected super-fast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

#### Features:

- Low Drive Power
- Low  $V_{CE(sat)}$
- Discrete Super-Fast Recovery Free-Wheel Diode
- Isolated Baseplate for Easy Heat Sinking

#### Applications:

- AC Motor Control
- UPS
- Battery Powered Supplies

#### Ordering Information:

Example: Select the complete part module number you desire from the table below -i.e. CM400DY-34A is a 1700V ( $V_{CES}$ ), 400 Ampere Dual IGBTMOD™ Power Module.

| Type | Current Rating<br>Amperes | $V_{CES}$<br>Volts (x 50) |
|------|---------------------------|---------------------------|
| CM   | 400                       | 34                        |

**CM400DY-34A**  
**Dual IGBTMOD™ A-Series Module**  
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**Absolute Maximum Ratings,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

| Ratings  | Symbol               | CM400DY-34A | Units            |
|--|----------------------|-------------|------------------|
| Junction Temperature   | $T_j$                | -40 to 150  | $^\circ\text{C}$ |
| Storage Temperature  | $T_{\text{stg}}$     | -40 to 125  | $^\circ\text{C}$ |
| Collector-Emitter Voltage (G-E Short)  | $V_{\text{CES}}$     | 1700        | Volts            |
| Gate-Emitter Voltage (C-E Short)   | $V_{\text{GES}}$     | $\pm 20$    | Volts            |
| Collector Current (DC, $T_C = 107^\circ\text{C}$ )*4   | $I_C$                | 400         | Amperes          |
| Peak Collector Current (Pulse Repetition)*2  | $I_{\text{CM}}$      | 800         | Amperes          |
| Maximum Collector Dissipation ( $T_C = 25^\circ\text{C}$ , $T_j \leq 150^\circ\text{C}$ )*2,*4 | $P_C$                | 3780        | Watts            |
| Emitter Current ( $T_C = 25^\circ\text{C}$ )   | $I_E^{*1}$           | 400         | Amperes          |
| Peak Emitter Current (Pulse Repetition)*2  | $I_{\text{EM}}^{*1}$ | 800         | Amperes          |
| Mounting Torque, M8 Main Terminal  | —                    | 96          | in-lb            |
| Mounting Torque, M6 Mounting   | —                    | 40          | in-lb            |
| Mounting Torque, M4 Mounting   | —                    | 15          | in-lb            |
| Weight   | —                    | 1200        | Grams            |
| Isolation Voltage (Main Terminal to Baseplate, $f = 60\text{Hz}$ , AC 1 min.)                  | $V_{\text{ISO}}$     | 3500        | Volts            |

**Static Electrical Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

| Characteristics                      | Symbol               | Test Conditions   | Min. | Typ. | Max. | Units         |
|--------------------------------------|----------------------|---|------|------|------|---------------|
| Collector-Cutoff Current             | $I_{\text{CES}}$     | $V_{\text{CE}} = V_{\text{CES}}$ , $V_{\text{GE}} = 0\text{V}$                      | —    | —    | 1.0  | mA            |
| Gate Leakage Current                 | $I_{\text{GES}}$     | $V_{\text{GE}} = V_{\text{GES}}$ , $V_{\text{CE}} = 0\text{V}$                      | —    | —    | 2.0  | $\mu\text{A}$ |
| Gate-Emitter Threshold Voltage       | $V_{\text{GE(th)}}$  | $I_C = 40\text{mA}$ , $V_{\text{CE}} = 10\text{V}$                                  | 5.5  | 7.0  | 8.5  | Volts         |
| Collector-Emitter Saturation Voltage | $V_{\text{CE(sat)}}$ | $I_C = 400\text{A}$ , $V_{\text{GE}} = 15\text{V}$ , $T_j = 25^\circ\text{C}^{*3}$  | —    | 2.2  | 2.8  | Volts         |
|                                      |                      | $I_C = 400\text{A}$ , $V_{\text{GE}} = 15\text{V}$ , $T_j = 125^\circ\text{C}^{*3}$ | —    | 2.45 | —    | Volts         |
| Total Gate Charge                    | $Q_G$                | $V_{\text{CC}} = 1000\text{V}$ , $I_C = 400\text{A}$ , $V_{\text{GE}} = 15\text{V}$ | —    | 2670 | —    | nC            |
| Emitter-Collector Voltage            | $V_{\text{EC}}^{*1}$ | $I_E = 400\text{A}$ , $V_{\text{GE}} = 0\text{V}^{*3}$                              | —    | —    | 3.0  | Volts         |

**Dynamic Electrical Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

| Characteristics               | Symbol               | Test Conditions  | Min.  | Typ. | Max. | Units         |
|-------------------------------|----------------------|--|-------|------|------|---------------|
| Input Capacitance             | $C_{\text{ies}}$     | $V_{\text{CE}} = 10\text{V}$ , $V_{\text{GE}} = 0\text{V}$           | —     | —    | 98.8 | nF            |
| Output Capacitance            | $C_{\text{oes}}$     |  | —     | —    | 11.2 | nF            |
| Reverse Transfer Capacitance  | $C_{\text{res}}$     |  | —     | —    | 2.1  | nF            |
| Inductive Load                | Turn-on Delay Time   | $V_{\text{CC}} = 1000\text{V}$ , $I_C = 400\text{A}$ ,               | —     | —    | 950  | ns            |
|                               | Rise Time            |  | $t_r$ | —    | —    | 300           |
| Switch Time                   | Turn-off Delay Time  | $V_{\text{GE}1} = V_{\text{GE}2} = 15\text{V}$ , $R_G = 1.2\Omega$ , | —     | —    | 1000 | ns            |
|                               | Fall Time            |  | $t_f$ | —    | —    | 350           |
| Diode Reverse Recovery Time   | $t_{\text{rr}}^{*1}$ | Switching Operation,   | —     | —    | 450  | ns            |
| Diode Reverse Recovery Charge | $Q_{\text{rr}}^{*1}$ | $I_E = 400\text{A}$  | —     | 40   | —    | $\mu\text{C}$ |

\*1 Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDI).

\*2 Pulse width and repetition rate should be such that device junction temperature ( $T_j$ ) does not exceed  $T_{j(\text{max})}$  rating.

\*3 Pulse width and repetition rate should be such as to cause negligible temperature rise.

\*4 Case temperature ( $T_C$ ), and heatsink temperature ( $T_f$ ) measured point is just under the chips.

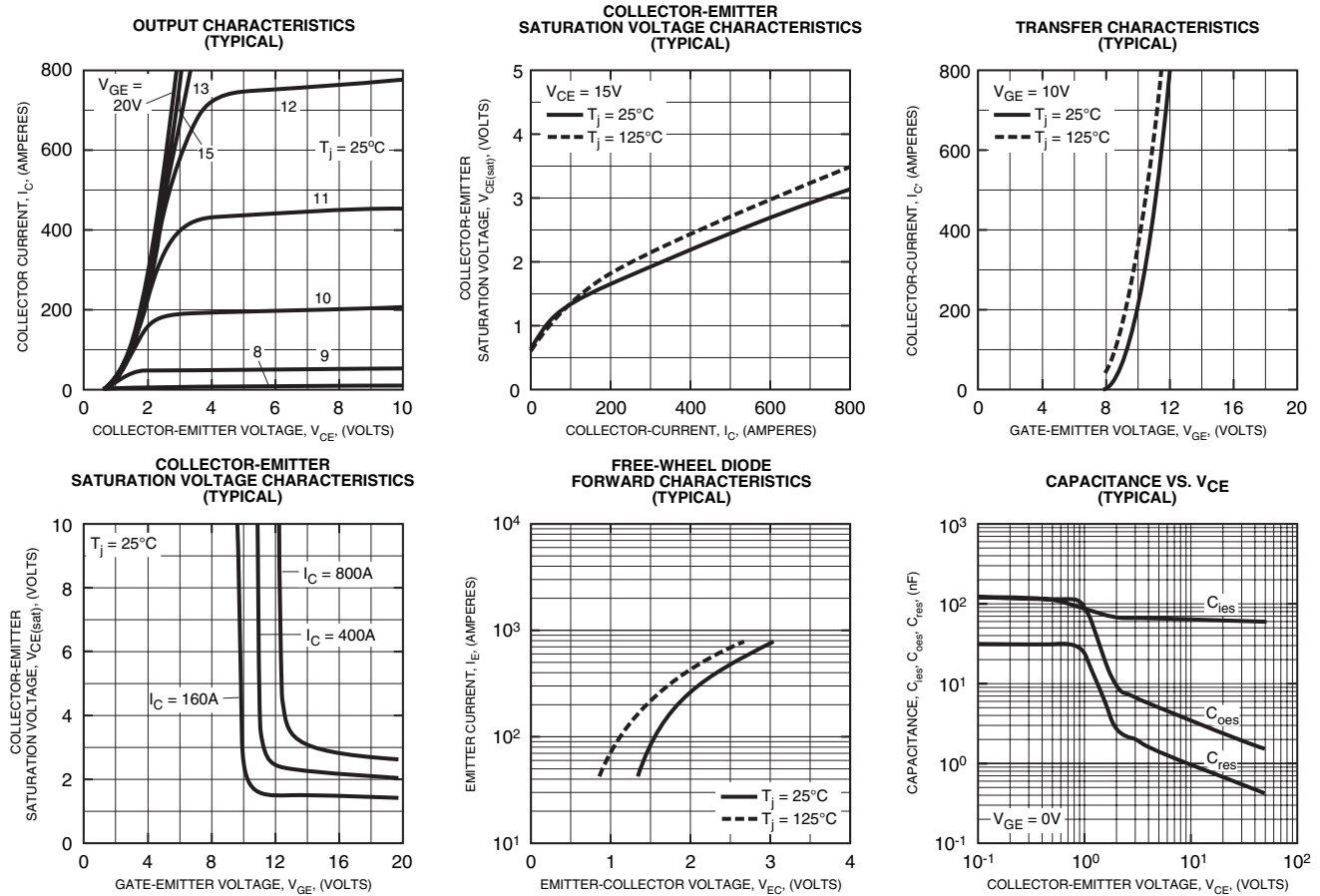
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**Thermal and Mechanical Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

| Characteristics                      | Symbol         | Test Conditions             | Min. | Typ.  | Max.  | Units              |
|--------------------------------------|----------------|-----------------------------|------|-------|-------|--------------------|
| Thermal Resistance, Junction to Case | $R_{th(j-c)Q}$ | Per IGBT*4                  | —    | —     | 0.033 | $^\circ\text{C/W}$ |
| Thermal Resistance, Junction to Case | $R_{th(j-c)D}$ | Per FWDI*4                  | —    | —     | 0.055 | $^\circ\text{C/W}$ |
| Contact Thermal Resistance           | $R_{th(c-f)}$  | Thermal Grease Applied*4,*5 | —    | 0.019 | —     | $^\circ\text{C/W}$ |
| External Gate Resistance             | $R_G$          |                             | 1.2  | —     | 12    | $\Omega$           |

\*4 Case temperature ( $T_C$ ), and heatsink temperature ( $T_f$ ) measured point is just under the chips.

\*5 Typical value is measured by using thermally conductive grease of  $\lambda = 0.9$  [W/(m • K)].



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